HF RoHS MC Series - DO-214

Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation

NOT APPLICABLE

Schematic Symbol

Description

MC Series DO-214 are low capacitance SIDACtor® devices designed to protect broadband equipment such as VOIP, DSL modems and DSLAMs from damaging overvoltage transients.

The series provides a surface mount solution that enables equipment to comply with global regulatory standards while limiting the impact to broadband signals.

Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings
- 40% lower capacitance than our Baseband Protectors, for applications that demand greater signal integrity

Applicable Global Standards

- TIA-968-A
- ITU K.20/21 Enhanced Level*
- ITU K.20/21 Basic Level*
- GR 1089 Inter-building*
- GR 1089 Intra-building*
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

*A-rated parts require series resistance

Electrical Characteristics

Part Number	Marking	V_{DRM} @I_{DRM}=5µA	V_S @100V/µs	I_H	I_S	I_T	V_T @I_T=2.2 Amps	Capacitance @1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P0080SAMCLRP	P-8AM	6	25	50	800	2.2	4	25	55
P0220SAMCLRP	P02AM	15	32	50	800	2.2	4	25	50
P0300SAMCLRP	P03AM	25	40	50	800	2.2	4	15	35
P0080SCMCLRP	P-8CM	6	25	50	800	2.2	4	25	75
P0220SCMCLRP	P02CM	15	32	50	800	2.2	4	30	65
P0300SCMCLRP	P03CM	25	40	50	800	2.2	4	25	45
P0640SCMCLRP	P06CM	58	77	150	800	2.2	4	55	85
P0720SCMCLRP	P07CM	65	88	150	800	2.2	4	50	75
P0900SCMCLRP	P09CM	75	98	150	800	2.2	4	45	70
P1100SCMCLRP	P11CM	90	130	150	800	2.2	4	45	70
P1300SCMCLRP	P13CM	120	160	150	800	2.2	4	40	60
P1500SCMCLRP	P15CM	140	180	150	800	2.2	4	35	55
P1800SCMCLRP	P18CM	170	220	150	800	2.2	4	35	50
P2100SCMCLRP	P21CM	180	240	150	800	2.2	4	30	50
P2300SCMCLRP	P23CM	190	260	150	800	2.2	4	30	50
P2600SCMCLRP	P26CM	220	300	150	800	2.2	4	30	45
P3100SCMCLRP	P31CM	275	350	150	800	2.2	4	30	45
P3500SCMCLRP	P35CM	320	400	150	800	2.2	4	25	40

Notes:
- Absolute maximum ratings measured at T_A= 25°C (unless otherwise noted).
- Devices are bi-directional (unless otherwise noted).

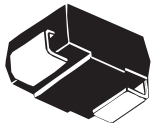
Surge Ratings

Series	I_{PP}									I_{TSM} 50/60 Hz	di/dt
	0.2x310 [1] 0.5x700 [2]	2x10 [1] 2x10 [2]	8x20 [1] 1.2x50 [2]	10x160 [1] 10x160 [2]	10x560 [1] 10x560 [2]	5x320 [1] 9x720 [2]	10x360 [1] 10x360 [2]	10x1000 [1] 10x1000 [2]	5x310 [1] 10x700 [2]		
	A min	A min	A min	A min	A min	A min	A min	A min	A min	A min	A/µs max
A	20	150	150	90	50	75	75	45	75	20	500
C	50	500	400	200	150	200	175	100	200	30	500

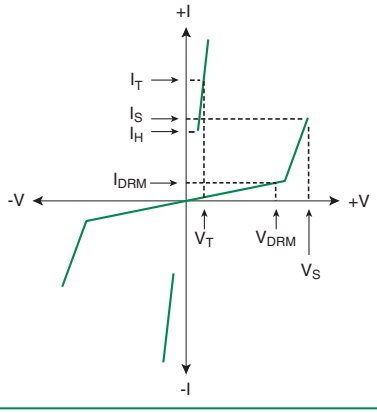
Notes:
1 Current waveform in µs
2 Voltage waveform in µs

- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product.
- I_{PP} ratings applicable over temperature range of -40°C to +85°C
- The device must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

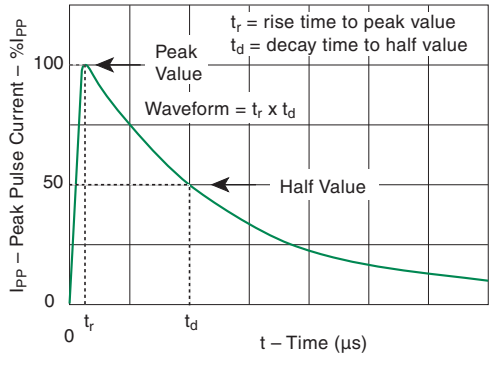
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
DO-214AA 	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	°C/W

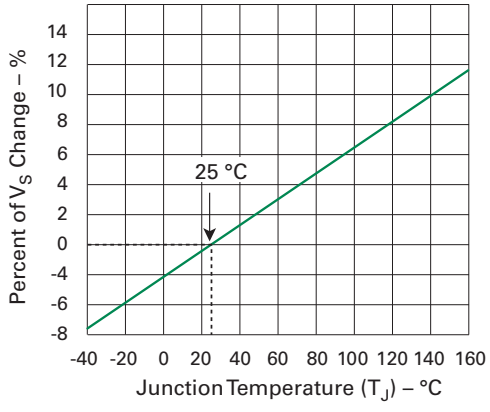
V-I Characteristics



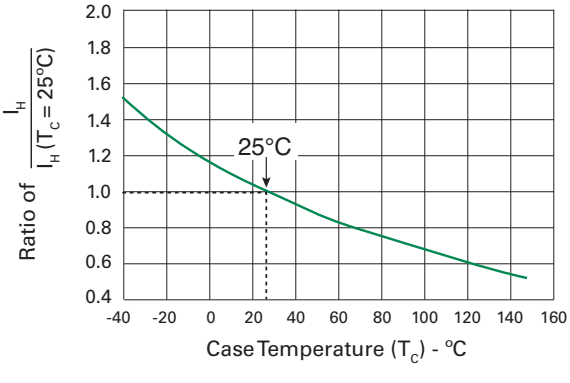
t_r x t_d Pulse Waveform



Normalized V_S Change vs. Junction Temperature



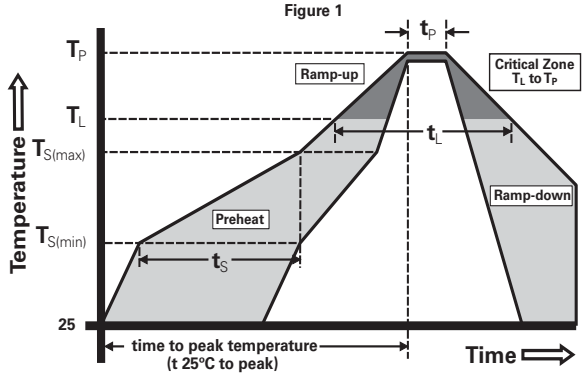
Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_P)		8 min. Max.
Do not exceed		+260°C

Figure 1



Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} (V_{AC} Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1